IPC ASSOCIATION CONNECT ELECTRONICS INDUSTR	© Copyright 2005, IPC.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute									Aaterials and	ials and Mfg Information				
Supplier Infor	mation						·									
Company name*			Company unique ID			Ţ	Unique ID Authority					Response Date*				
onsemi												2024-04-30				
Contact Name		Title - Contact			I	Phone - Contact*				Emai	Email - Contact*					
Product-Env-Stev	wards	Product Enviro Compliance				NA				Prod	Product-Env-Stewards@onsemi.com					
uthorized Repres	sentative*	Title - Representative			I	Phone - Representative*				Emai	Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance				NA				Prod	Product-Env-Stewards@onsemi.com				
Reques	ster Item Number	Mfr Item	em Number Mfr Item Name				Effective Dat	e Versio	sion Manufacturing Site		ite	Weight*		UOM	Unit Type	
		FOD3125SD 8PW 2.		8PW 2.5A GD D	BPW 2.5A GD DIP		2024-04-30		I	LITEONFG		598.	1311	mg	Each	
Ianufacturing	g Proccess Informatio	n		,								1			İ	
Termina	al Plating / Grid Array Material		Terminal Base Alloy		J-STD-020 M	MSL Rating Peal		eak Process Body Temperature		e Max Time at	Peak Tempe	rature	Number of Reflow Cycles			
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 1		1		260		C 30		sec	seconds		3		
comments																
vel 1 - maximum	time at peak temperature	during so	ldering is 10-3	0 seconds												
or more informa	tion regarding material cor	nposition	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.131	mg	Supplier	Silicon (Si)	7440-21-3		1.131	mg
Die Attach	0.25	mg	Supplier	Silver (Ag)	7440-22-4		0.205	mg
			Supplier	Dicyandiamine	461-58-5		0.0025	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0425	mg
Lead Frame	113.416	mg	Supplier	Zinc (Zn)	7440-66-6		0.1361	mg
			Supplier	Iron (Fe)	7439-89-6		2.6653	mg
			Supplier	Copper (Cu)	7440-50-8		110.5806	mg
			Supplier	Phosphorus (P)	7723-14-0		0.034	mg
Mold Compound-White	459.747	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		114.9368	mg
			В	Brominated Bisphenol A Diglycidyl Ether	40039-93-8		13.7924	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		62.0658	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		13.7924	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		229.8735	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		25.2861	mg
Plating	1.58413	mg	Supplier	Silver (Ag)	7440-22-4		0.0242	mg
			Supplier	Palladium (Pd)	7440-05-3		0.0566	mg
			В	Nickel (Ni)	7440-02-0		1.471	mg
			Supplier	Gold (Au)	7440-57-5		0.0323	mg
Protective Coating	6.13	mg	Supplier	Poly(dimethylsiloxane), hydroxy terminated	70131-67-8		3.065	mg
			Supplier	Ethylbenzene	100-41-4		0.613	mg
			Supplier	Filler (SiO2)	68909-20-6		1.1647	mg
			Supplier	Misc.	Proprietary Data		0.0613	mg
			Supplier	Xylene	1330-20-7		1.226	mg
Wire Bond - Au	15.873	mg	Supplier	Gold (Au)	7440-57-5		15.873	mg